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500.38665CX1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SHIMOKAWA et al.

Serial No.: 09/972,178

Filed: October 9, 2001

For: PB-FREE SOLDER-CONNECTED STRUCTURE AND
ELECTRONIC DEVICE

Group: 1775

Examiner: J. J. Zimmerman

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. 1.97 & 1.98

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 21, 2003

Sir:

Pursuant to Applicants' duty of disclosure, enclosed please find a copy of a newly discovered document, for consideration by the Examiner in connection with the above-identified application. Also enclosed is a Form, substantially equivalent to Form PTO-1449, listing the enclosed document. This form also lists documents (copies of which are also enclosed) cited in an Office Action mailed July 29, 2003, in copending (related) Application No. 09/971,566, filed October 9, 2001, which claims priority under 35 USC §120 of a same prior application, No. 09/581,631, upon which the above-identified application claims priority under 35 USC §120.

This Information Disclosure Statement is being submitted subsequent to issuance of a Final rejection in connection with the above-identified application, the application being under a Final rejection, but in an application in which the Issue Fee has not been paid. For satisfying the requirements of 37 CFR §1.97(d), the fee set

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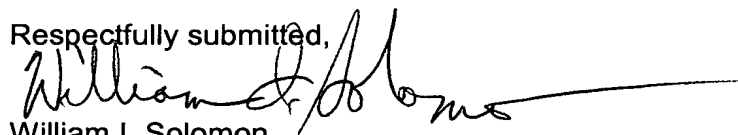
forth in 37 CFR §1.17(p) is enclosed, and the following Statement is made under 37 CFR §1.97(e)(2):

No item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned after making reasonable inquiry, no item of information contained in this Information Disclosure Statement was known to any individual designated in 37 CFR §1.56(c), more than three months prior to the filing of this Information Disclosure Statement.

In view of the foregoing, it is respectfully submitted that all applicable requirements of 37 CFR §1.97 and §1.98 have been satisfied, in connection with present submission of the enclosed documents. Accordingly, consideration of the enclosed documents, upon further consideration of the above-identified application, is respectfully requested.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit account of Antonelli, Terry, Stout & Kraus, LLP, Deposit Account No. 01-2135 (Case: 500.38665CX1), and please credit any excess fees to such deposit account.

Respectfully submitted,


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Attachments

FORM PTO-1449 U.S. Department of Commerce
(Rev. 4/92) Patent and Trademark Office

ATTY. DOCKET NO.
500.38665CX1

SERIAL NO.
09/972,178

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

APPLICANT
SHIMOKAWA et al.

FILING DATE
October 9, 2001

GROUP
1775

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER								DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	3	6	0	7	2	5	3		9/71	CAIN et al.			
	5	5	6	9	4	3	3		10/96	CHEN et al.			
	6	1	8	7	1	1	4		2/01	OGASHIWA et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER								DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
													YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

1	Manfred JORDAN, "Lead-Free Tin Alloys as Substitutes For Tin-Lead Alloy Plating", Trans IMF, 1997, pp. 149-153.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation is considered, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.